

### **IGBT** Module

### SK 30 GD 128

**Preliminary Data** 

#### **Features**

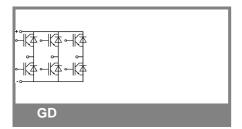
- · Compact design
- · One screw mounting
- Heat transfer and isolation through direct copper bonding aluminium oxide ceramic (DBC)
- · High short circuit capability
- SPT=Soft-Puntch-Through technology
- V<sub>ce(sat)</sub> with positive coefficient

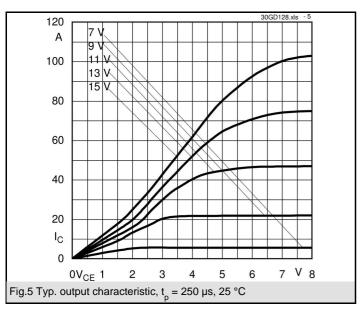
### **Typical Applications**

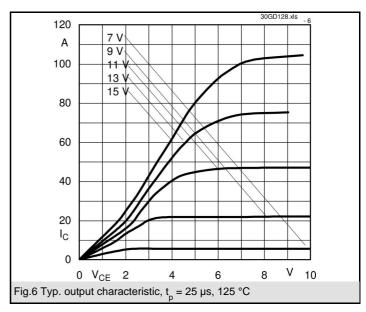
- Switching (not for linear use)
- Inverter
- · Switched mode power supplies
- UPS

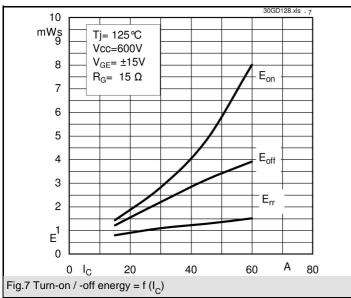
Absolute	Maximum Ratings	T <sub>s</sub> = 25 °C, unless otherwise specified					
Symbol	Conditions	Values	Units				
IGBT							
$V_{CES}$		1200	V				
$V_{GES}$		± 20	V				
I <sub>C</sub>	$T_s = 25 (80) ^{\circ}C;$	35 (25)	Α				
I <sub>CM</sub>	$t_p < 1 \text{ ms}; T_s = 25 (80) ^{\circ}\text{C};$	70 (50)	Α				
T <sub>j</sub>	·	- 40 <b>+</b> 150	°C				
Inverse/Freewheeling CAL diode							
I <sub>F</sub>	T <sub>s</sub> = 25 (80) °C;	37 (25)	Α				
$I_{FM} = -I_{CM}$	$t_p$ < 1 ms; $T_s$ = 25 (80) °C;	74 (50)	Α				
T <sub>j</sub>		- 40 <b>+</b> 150	°C				
T <sub>stg</sub>		- 40 + 125	°C				
T <sub>sol</sub>	Terminals, 10 s	260	°C				
V <sub>isol</sub>	AC 50 Hz, r.m.s. 1 min. / 1 s	2500 / 3000	V				

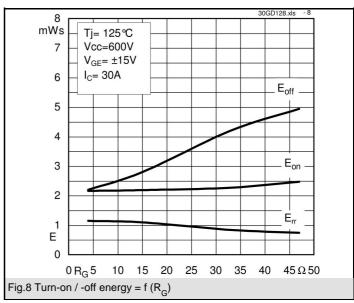
Characteristics		$T_s$ = 25 °C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V <sub>CE(sat)</sub>	I <sub>C</sub> = 25 A, T <sub>i</sub> = 25 (125) °C		1,9 (2,1)		V
$V_{GE(th)}$	$V_{CE} = V_{GE}$ ; $I_{C} = A$	4,5	5,5	6,5	V
C <sub>ies</sub>	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; 1 \text{ MHz}$		2,5		nF
$R_{th(j-s)}$	per IGBT			1	K/W
	per module				K/W
	under following conditions:				
$t_{d(on)}$	V <sub>CC</sub> = 600 V , V <sub>GE</sub> = ± 15 V		55		ns
t <sub>r</sub>	I <sub>C</sub> = 30 A, T <sub>j</sub> = 125 °C		26		ns
$t_{d(off)}$	$R_{Gon} = R_{Goff} = 15 \Omega$		284		ns
t <sub>f</sub>			40		ns
$E_{on} + E_{off}$	Inductive load		4,99		mJ
Inverse/F	reewheeling CAL diode				
$V_F = V_{EC}$	I <sub>F</sub> = 25 A; T <sub>i</sub> = 25 (125) °C		2 (1,8)		V
V <sub>(TO)</sub>	$T_{i} = (125)  ^{\circ}C$		(1)	(1,2)	V
r <sub>T</sub>	$T_{j} = (125)  ^{\circ}C$		(32)	(44)	mΩ
$R_{th(j-s)}$				1,2	K/W
	under following conditions:				
I <sub>RRM</sub>	I <sub>F</sub> = 22 A; V <sub>R</sub> = 600 V		25		Α
$Q_{rr}$	$dI_F/dt = -500 A/\mu s$		4,5		μC
E <sub>off</sub>	V <sub>GE</sub> = 0 V; T <sub>j</sub> = 125 °C		1		mJ
Mechanic	al data	•			•
M1	mounting torque			2	Nm
w			19		g
Case	SEMITOP® 3		T 12		

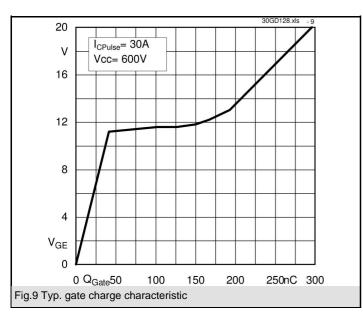


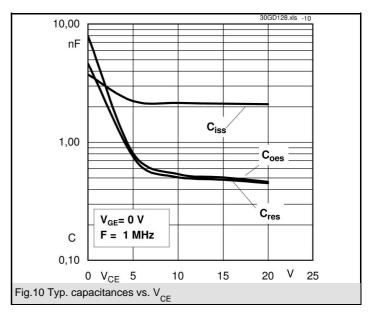


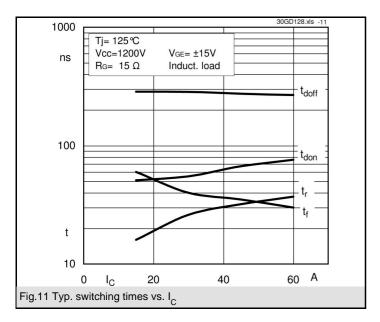


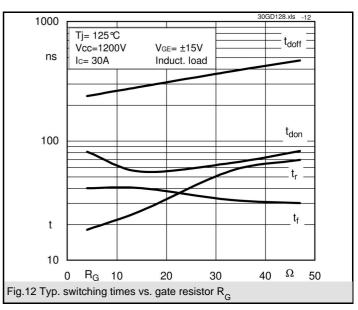


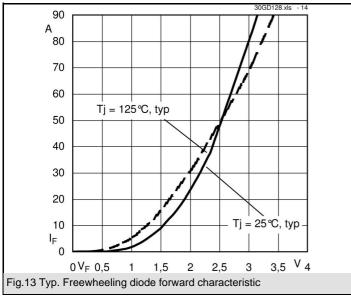


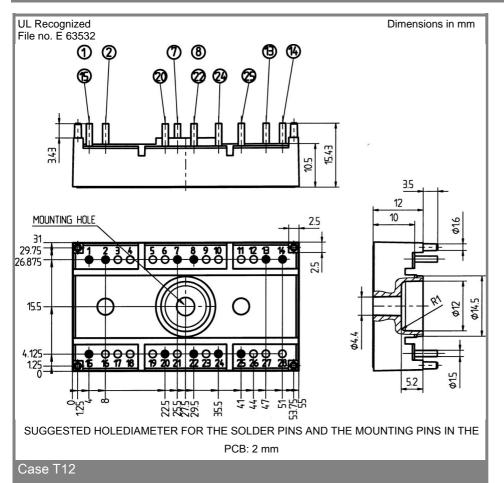


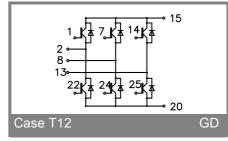












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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